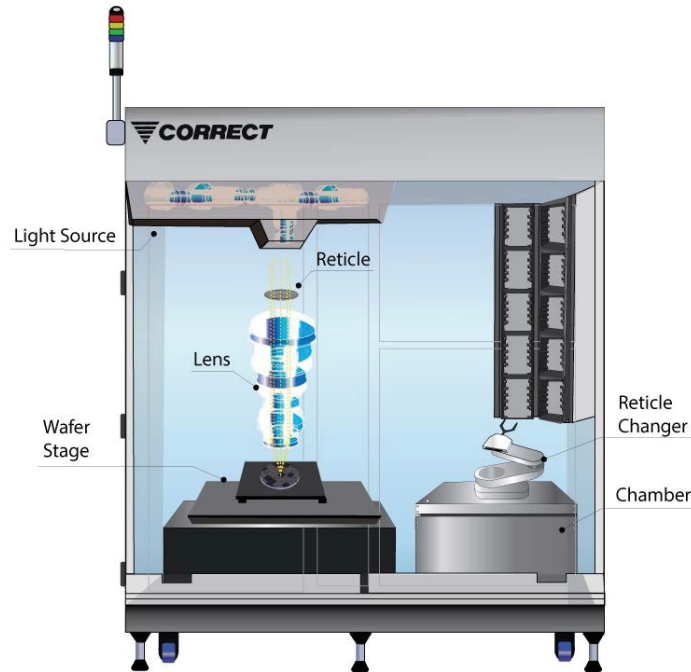


# Projection Aligner



## Specifications

Application	Model	Exposure Area	Wavelength	Alignment	NA	Resolution
Power Device	SPF-150 Series	Φ150mm	365nm	Single Sided	0.14	2.0μm
CMOS Back Wiring	SPS-300 Series	Φ300mm(Φ150mm×4step)	365nm	Double Sided	0.08	3.5μm
2.5D&3D Packaging	SPF-150 Series	Φ150mm	365nm	Single Sided	0.14	2.0μm
LED (PSS)	SPF-100 Series	Φ100mm	365nm	Double Sided	0.17	1.4μm

\*We can also manufacture RTR projecting exposure system for FPC (flexible printed circuits).

\*Uses Seiwa Own designed and manufactured Projection lens

## Features

- Projection aligner resolves problems below from contact and proximity exposure system
- Adhesive Failure from Contact / Proximity exposure
- Projection aligner is Non-Contact exposure system
- Variability of Gap between mask and substrate
- Projection aligner cancels variability of Gap by its larger focal depth.
- Smaller focal depth problem from Contact/ Proximity exposure
- Projection aligner provides large focal depth of (1μm)
- Both side Alignment Accuracy: Topside ±1μm
- Capacity: 90 wafers / hr.
- Backside : ±1μm

## Mail Market

- 1) CMOS
- 2) Power device (Backside wiring)  
\*Thick Resist ,High Step Patterning
- 3) MEMS
- 4) LED (PSS)
- 5) Roll to Roll

## Options

- 1) Reticle Stocker
- 2) Automatic Reticle changer
- 3) Fully Automated / Semi Automated option
- 4) Magnification adjuster